ASSOCIATION CONNECTING LECTRONICS INDUSTRIES® INDUSTRIES®	PC. Bannockl	ourn, Illinois, A	ll rights reserved utions.	under both	This docume level parts, t	ent is a declarati the declaration e	on of the su	ibstances s s all lower	within the manufactu e level materials for w	rer listed	tem. Note: nanufacture	if the item is an as r has engineering	sembly with lower responsibility.	
IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information									
Supplier Information														
Company name* Company unique				Unique			Inique ID Authority			Respon	Response Date*			
onsemi										2024-09	-23			
Contact Name		Title - Contac	et			Phone - Contac	Phone - Contact* Email - Contact*							
Product-Env-Stewards	Product Enviro Compliance				NA			Product-Env-Stewards@onsemi.com						
Authorized Representative*	Title - Repres	e - Representative			Phone - Representative*			Email -	Email - Representative*					
Product-Env-Stewards	Product Envir	oduct Enviro Compliance NA Product-Env-Stewards@ons				vards@onsemi.co	m							
Requester Item Number	Requester Item Number Mfr Item Num		umber Mfr Item Name			Effective Date	Version	Ν	Manufacturing Site		Weight*	UOM	Unit Type	
	ASX344 A0-TRB	44ATSC00XUE VGA 1/4 CIS SOC RBR		C		2024-09-23		N	MY5		180.8	mg	Each	
Manufacturing Proccess Informat	ion													
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSI					Rating	Peak Proc	ess Body To	emperatur	e Max Time at Peak	Tempera	ture Num	ber of Reflow Cyc	les	
SnAgCu CU Alloy 3						260		С	30	seco	nds 3			
Comments														
ATTENTION: MSL 3 Rated item requires	Bake and E	Dry Pack (after	electrical test)											
For more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the
Supplier Digital Signature Ra	stislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	22.05	mg		Misc.	proprietary data		0.0838	mg
			Supplier	Silicon (Si)	7440-21-3		21.7479	mg
			Supplier	Aluminum (Al)	7429-90-5		0.2183	mg
Die Attach	0.97	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.3638	mg
			Supplier	Ethylene Glycol	107-21-1		0.0097	mg
			Supplier	Sulfonium (Thiodi-4,1-phenylene)	89452-37-9		0.0291	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.2037	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.3638	mg
Imaging Lens	34.06	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		1.7926	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		1.7926	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		0.1795	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		1.7926	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		1.7926	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		1.7926	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		24.9176	mg
Lid Attach	1.05	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.315	mg
			Supplier	Filler (SiO2)	68909-20-6		0.0525	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.3412	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.3412	mg
Mold Compound-Black	40.48	mg		Phenolic Resin	proprietary data		6.072	mg
			Supplier	Oxirane	39817-09-9		6.072	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		1.2144	mg
			Supplier	Carbon Black (C)	1333-86-4		0.4048	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		25.9072	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.8096	mg
older Ball	30.61	mg	Supplier	Silver (Ag)	7440-22-4		0.9183	mg
			Supplier	Tin (Sn)	7440-31-5		29.5387	mg
			Supplier	Copper (Cu)	7440-50-8		0.1531	mg
Substrate and Solder Mask	51.12	mg	Supplier	Bis(3-ethyl-5-methyl-4- maleimidophenyl)methane	105391-33-1		0.5725	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3		6.6252	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0767	mg

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6	1.1911	mg
			Supplier	Cyanic acid (1-methylethylidene)di-4,1- phenylene ester homopolymer	25722-66-1	0.5725	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9	0.2965	mg
			Supplier	Chromium (Cr)	7440-47-3	0.0051	mg
			Supplier	Acetophenone Derivative	Proprietary Data	1.7841	mg
			Supplier	Carbon Black (C)	1333-86-4	0.2965	mg
			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	0.2965	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2	6.1344	mg
			В	Nickel (Ni)	7440-02-0	0.7208	mg
			Supplier	Gold (Au)	7440-57-5	0.0256	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	3.5733	mg
			Supplier	Formaldehyde Polymer	9003-36-5	0.5725	mg
			Supplier	Copper (Cu)	7440-50-8	19.1496	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	9.2272	mg
Wire Bond - Au	0.46	mg	Supplier	Gold (Au)	7440-57-5	0.46	mg